



Material Content Data Sheet



Sales Product Name		ISO1H812G		Issued		3. July 2019		
MA#		MA001241470						
Package		PG-DSO-36-21		Weight*		2046.11 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.123	0.05	0.05	549	549
chip_2	inorganic material	silicon	7440-21-3	1.164	0.06	0.06	569	569
chip_3	inorganic material	silicon	7440-21-3	16.733	0.82	0.82	8178	8178
leadframe	inorganic material	phosphorus	7723-14-0	0.383	0.02		187	
	non noble metal	zinc	7440-66-6	1.533	0.07		749	
	non noble metal	iron	7439-89-6	30.652	1.50		14981	
wire	non noble metal	copper	7440-50-8	1244.598	60.83	62.42	608275	624192
	noble metal	gold	7440-57-5	3.870	0.19	0.19	1891	1891
	encapsulation	organic material	carbon black	1333-86-4	1.438	0.07		703
leadfinish	plastics	epoxy resin	-	66.130	3.23		32320	
	inorganic material	silicondioxide	60676-86-0	651.233	31.83	35.13	318278	351301
	non noble metal	tin	7440-31-5	16.150	0.79	0.79	7893	7893
plating	noble metal	silver	7440-22-4	0.741	0.04	0.04	362	362
solder	non noble metal	tin	7440-31-5	0.101	0.00		49	
	noble metal	silver	7440-22-4	0.151	0.01		74	
glue	non noble metal	lead	7439-92-1	9.819	0.48	0.49	4799	4922
	plastics	Polyimide	26023-21-2	0.292	0.01	0.01	143	143
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com